

芯伯乐®
X I N B O L E

Product Specification

XBLW SN74LS48

BCD-to-Seven-Segment Common Cathode

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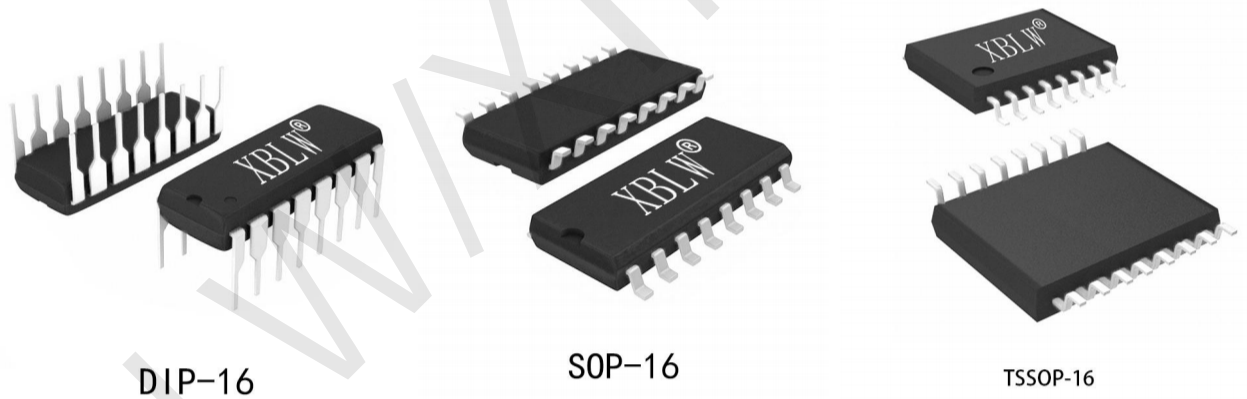
Description

The SN74LS48 feature active-low outputs designed for driving common-anode LEDs or incandescent indicators directly. Display patterns for BCD input counts above 9 are unique symbols to authenticate input conditions.

The SN74LS48 incorporate automatic leading and/or trailing-edge zero-blanking control (\overline{RBI} and \overline{RBO}). Lamp test (\overline{LT}) of these types may be performed at any time when the $\overline{BI}/\overline{RBO}$ node is at a high level. The SN74LS48 contain an overriding blanking input (\overline{BI}), which can be used to control the lamp intensity by pulsing or to inhibit the outputs.

Features

- CMOS Input levels
- Internal pull-ups eliminate need for external resistors Lamp-test provision
- Leading/trailing zero suppression
- Specified from -20°C to +85°C
- Packaging information: DIP16/SOP16/TSSOP16



Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LS48N	DIP-16	74LS48N	Tube	1000Pcs/Box
XBLW SN74LS48DTR	SOP-16	74LS48	Tape	2500Pcs/Reel
XBLW SN74LS48TDTR	TSSOP-16	74LS48	Tape	3000Pcs/Reel

Block Diagram

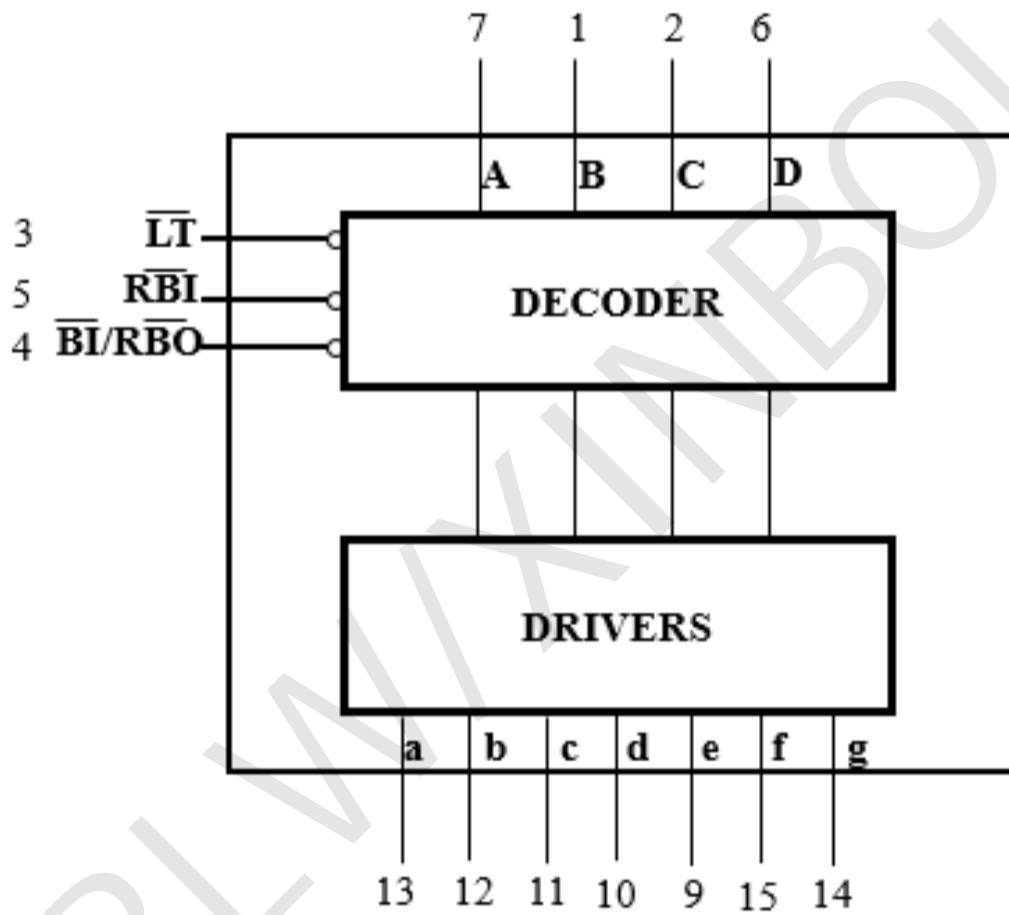
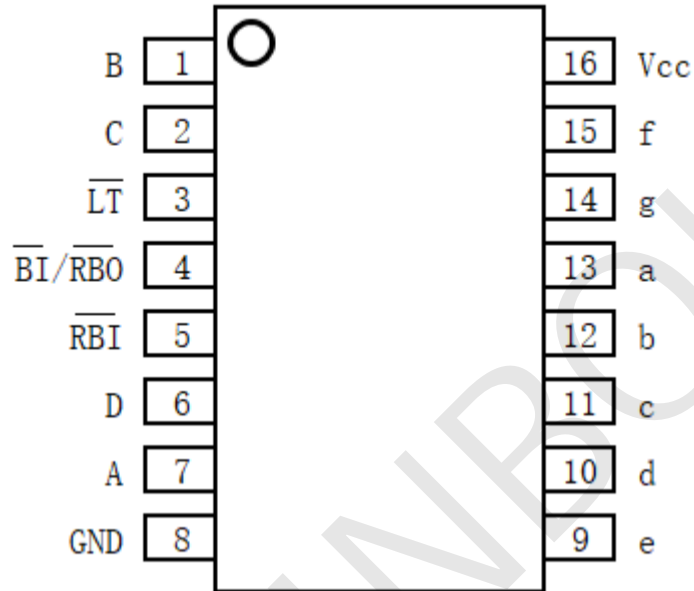


Figure 1. Logic symbol

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	B	data input
2	C	data input
3	$\overline{\text{LT}}$	lamp test
4	$\overline{\text{BI}}/\overline{\text{RBO}}$	blanking input/ripple blanking output
5	$\overline{\text{RBI}}$	ripple blanking input
6	D	data input
7	A	data input
8	GND	ground (0V)
9	e	data output
10	d	data output
11	c	data output
12	b	data output
13	a	data output
14	g	data output
15	f	data output
16	V _{CC}	supply voltage

Function Table

Decimal or function	Input						$\overline{\text{BI/RBO}}$	Output						
	$\overline{\text{LT}}$	$\overline{\text{RBI}}$	D	C	B	A		a	b	c	d	e	f	g
0	H	H	L	L	L	L	H	H	H	H	H	H	H	L
1	H	X	L	L	L	H	H	L	H	H	L	L	L	L
2	H	X	L	L	H	L	H	H	H	L	H	H	L	H
3	H	X	L	L	H	H	H	H	H	H	H	L	L	H
4	H	X	L	H	L	L	H	L	H	H	L	L	H	H
5	H	X	L	H	L	H	H	H	L	H	H	L	H	H
6	H	X	L	H	H	L	H	L	L	H	H	H	H	H
7	H	X	L	H	H	H	H	H	H	H	L	L	L	L
8	H	X	H	L	L	L	H	H	H	H	H	H	H	H
9	H	X	H	L	L	H	H	H	H	H	L	L	H	H
10	H	X	H	L	H	L	H	L	L	L	H	H	L	H
11	H	X	H	L	H	H	H	L	L	H	H	L	L	H
12	H	X	H	H	L	L	H	L	H	L	L	L	H	H
13	H	X	H	H	L	H	H	H	L	L	H	L	H	H
14	H	X	H	H	H	L	H	L	L	L	H	H	H	H
15	H	X	H	H	H	H	H	L	L	L	L	L	L	L
$\overline{\text{BI}}$	X	X	X	X	X	X	L	L	L	L	L	L	L	L
$\overline{\text{RBI}}$	H	L	L	L	L	L	L	L	L	L	L	L	L	L
$\overline{\text{LT}}$	L	X	X	X	X	X	H	H	H	H	H	H	H	H

Note:

- [1] H=HIGH voltage level; L=LOW voltage level; X=don't care.
- [2] The blanking input ($\overline{\text{BI}}$) must be open or held at a high logic level when output functions 0 through 15 are desired. The ripple-blanking input ($\overline{\text{RBI}}$) must be open or high if blanking of a decimal zero is not desired.
- [3] When a low logic level is applied directly to the blanking input ($\overline{\text{BI}}$), all segment outputs are off regardless of the level of any other input.
- [4] When ripple-blanking input ($\overline{\text{RBI}}$) and inputs A, B, C, D are at a low level with the lamp test input high, all segment outputs go off and the ripple-blanking output ($\overline{\text{RBO}}$) goes to a low level (response condition).
- [5] When the blanking input/ripple blanking output ($\overline{\text{BI/RBO}}$) is open or held high and a low is applied to the lamp test input, all segment outputs are on.

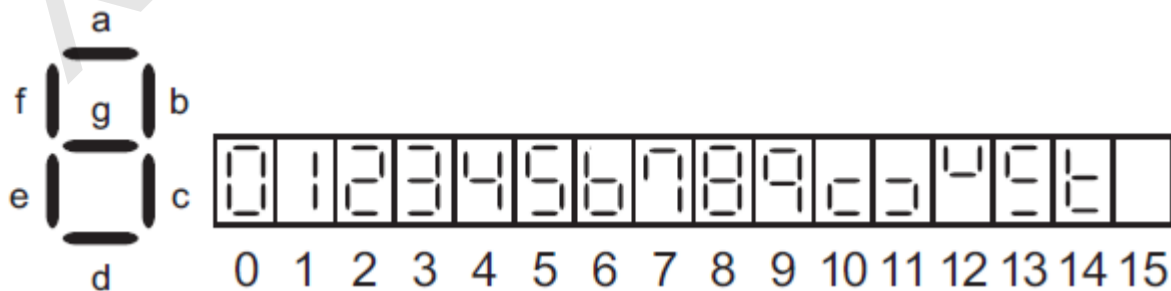


Figure 2. Segment identification

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND(ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V_{CC}	-	-0.5	+7.0	V
input clamping current	I_{IK}	$V_I < -0.5V$ or $V_I > V_{CC}+0.5V$	-	± 20	mA
output clamping current	I_{OK}	$V_O < -0.5V$ or $V_O > V_{CC}+0.5V$	-	± 20	mA
output current	I_O	$-0.5V < V_O < V_{CC}+0.5V$	-	± 25	mA
supply current	I_{CC}	-	-	+50	mA
ground current	I_{GND}	-	-50	-	mA
storage temperature	T_{stg}	-	-65	+150	°C
total power dissipation	P_{tot}	-	-	500	mW
soldering temperature	T_L	10s	DIP	245	°C
			SOP	250	

Note:

[1] For DIP16 packages: above 70°C the value of P_{tot} derates linearly with 12mW/K.

[2] For SOP16 packages: above 70°C the value of P_{tot} derates linearly with 8mW/K.

[3] For (T)SSOP16 packages: above 60°C the value of P_{tot} derates linearly with 5.5mW/K.

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V_{CC}	-	2.0	5.0	6.0	V
input voltage	V_I	-	0	-	V_{CC}	V
output voltage	V_O	-	0	-	V_{CC}	V
input transition rise and fall rate	$\Delta t/\Delta V$	$V_{CC}=2.0V$	-	-	625	ns/V
		$V_{CC}=4.5V$	-	1.67	139	ns/V
		$V_{CC}=6.0V$	-	-	83	ns/V
ambient temperature	T_{amb}	-	-20	-	+85	°C

Electrical Characteristics

DC Characteristics 1

($T_{amb} = 25^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	1.2	-	V	
		$V_{CC}=4.5\text{V}$	3.15	2.4	-	V	
		$V_{CC}=6.0\text{V}$	4.2	3.2	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	0.8	0.5	V	
		$V_{CC}=4.5\text{V}$	-	2.1	1.35	V	
		$V_{CC}=6.0\text{V}$	-	2.8	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I=V_{IH}$ or V_{IL}	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	2.0	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	4.5	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	6.0	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.98	4.32	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.48	5.81	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH}$ or V_{IL}	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	0	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	0	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	0.15	0.26	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	0.16	0.26	V
input leakage current	I_I	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	± 0.1	μA	
supply current	I_{CC}	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	8.0	μA	
input capacitance	C_I	-	-	3.5	-	pF	

DC Characteristics 2

($T_{amb} = -20^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level input voltage	V_{IH}	$V_{CC}=2.0\text{V}$	1.5	-	-	V	
		$V_{CC}=4.5\text{V}$	3.15	-	-	V	
		$V_{CC}=6.0\text{V}$	4.2	-	-	V	
LOW-level input voltage	V_{IL}	$V_{CC}=2.0\text{V}$	-	-	0.5	V	
		$V_{CC}=4.5\text{V}$	-	-	1.35	V	
		$V_{CC}=6.0\text{V}$	-	-	1.8	V	
HIGH-level output voltage	V_{OH}	$V_I=V_{IH}$ or V_{IL}	$I_O=-20\mu\text{A}; V_{CC}=2.0\text{V}$	1.9	-	-	V
			$I_O=-20\mu\text{A}; V_{CC}=4.5\text{V}$	4.4	-	-	V
			$I_O=-20\mu\text{A}; V_{CC}=6.0\text{V}$	5.9	-	-	V
			$I_O=-4.0\text{mA}; V_{CC}=4.5\text{V}$	3.84	-	-	V
			$I_O=-5.2\text{mA}; V_{CC}=6.0\text{V}$	5.34	-	-	V
LOW-level output voltage	V_{OL}	$V_I=V_{IH}$ or V_{IL}	$I_O=20\mu\text{A}; V_{CC}=2.0\text{V}$	-	-	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=4.5\text{V}$	-	-	0.1	V
			$I_O=20\mu\text{A}; V_{CC}=6.0\text{V}$	-	-	0.1	V
			$I_O=4.0\text{mA}; V_{CC}=4.5\text{V}$	-	-	0.33	V
			$I_O=5.2\text{mA}; V_{CC}=6.0\text{V}$	-	-	0.33	V
input leakage current	I_I	$V_I=V_{CC}$ or GND; $V_{CC}=6.0\text{V}$	-	-	± 1.0	μA	
supply current	I_{CC}	$V_I=V_{CC}$ or GND; $I_O=0\text{A}; V_{CC}=6.0\text{V}$	-	-	80	μA	

AC Characteristics

($T_{amb}=25^{\circ}C$, voltages are referenced to GND (ground=0V), unless otherwise specified.)

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit
HIGH to LOW propagation delay	t_{PHL}	$V_{CC}=5.0V$; $C_L=15pF$	output from A input; $R_L=4k\Omega$	-	-	100	ns
			output (a-f only) from \overline{RBI} input; $R_L=6k\Omega$	-	-	100	ns
LOW to HIGH propagation delay	t_{PLH}	$V_{CC}=5.0V$; $C_L=15pF$	output from A input; $R_L=4k\Omega$	-	-	100	ns
			output (a-f only) from \overline{RBI} input; $R_L=6k\Omega$	-	-	100	ns

Testing Circuit

AC Testing Circuit

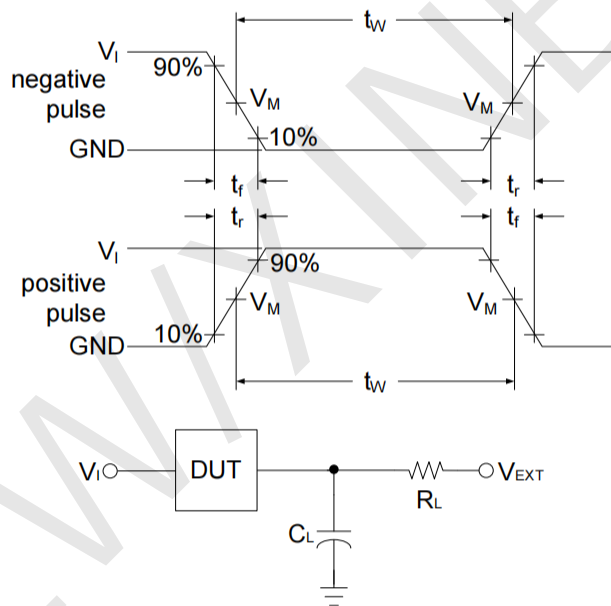


Figure 3. Test circuit for measuring switching times

C_L includes probe and jig capacitance.

Test Data

Type	Input		Load		V_{EXT}
	V_I	$t_r = t_f$	C_L	R_L	t_{PHL}/t_{PLH}
SN74LS48	V_{CC}	3.0ns	15pF	4K Ω	V_{CC}

AC Testing Waveforms

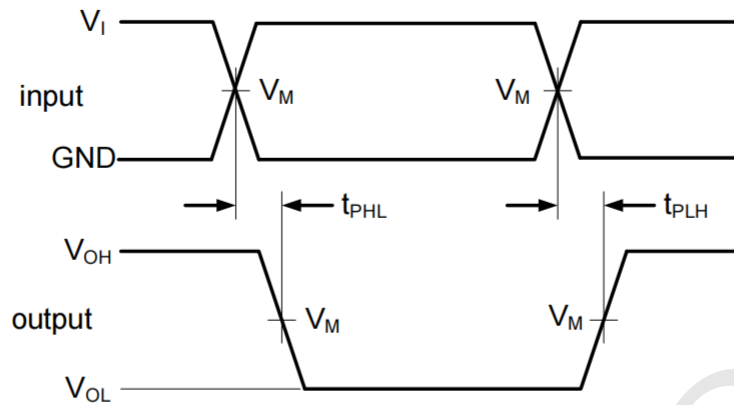


Figure 4. The data input to output propagation delays

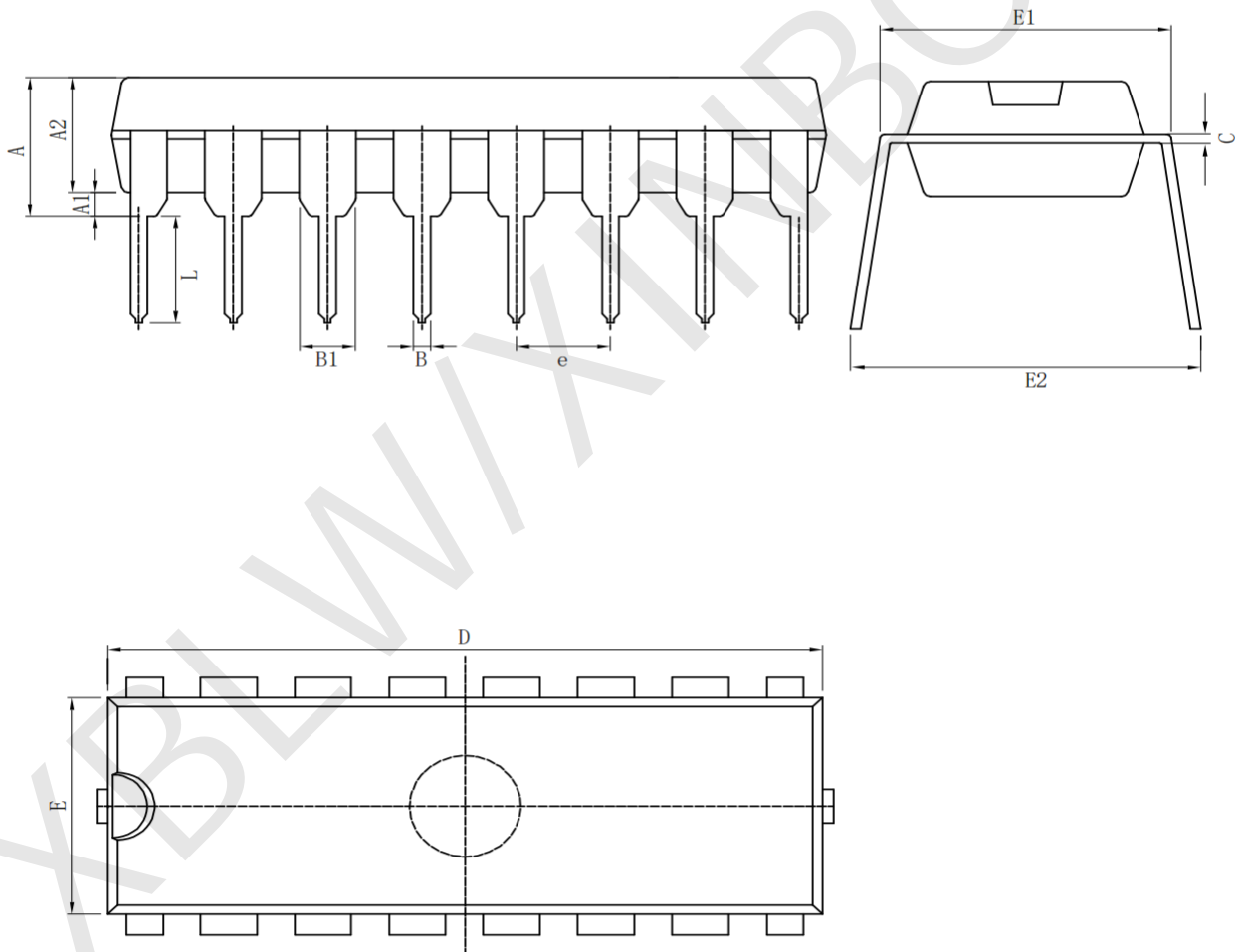
Measurement Points

Type	Input	Output
	V_M	V_M
SN74LS48	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

Package Information

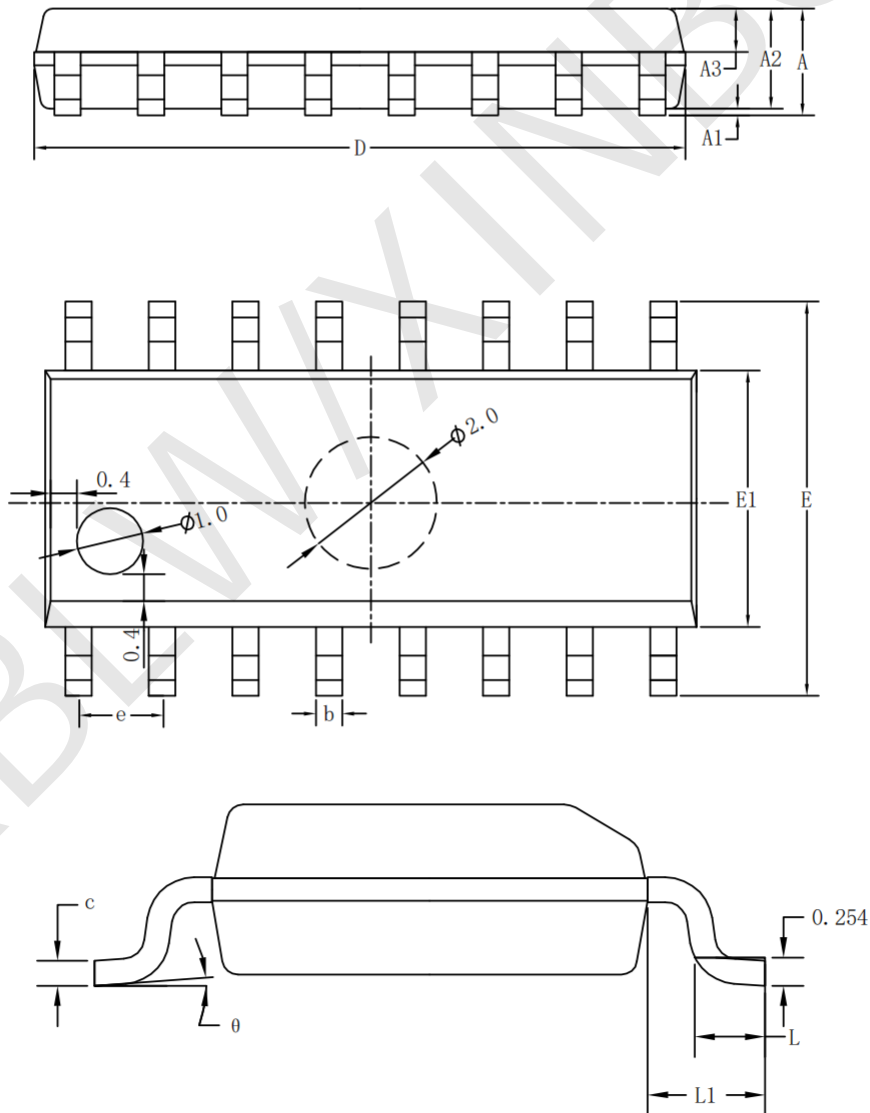
· DIP-16

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	3.710	4.310	A	0.146	0.170
A1	0.510		A1	0.020	
A2	3.200	3.600	A2	0.126	0.142
B	0.380	0.570	B	0.015	0.022
B1	1.524 (BSC)		B1	0.060 (BSC)	
C	0.204	0.360	C	0.008	0.014
D	18.80	19.20	D	0.740	0.756
E	6.200	6.600	E	0.244	0.260
E1	7.320	7.920	E1	0.288	0.312
e	2.540 (BSC)		e	0.100 (BSC)	
L	3.000	3.600	L	0.118	0.142
E2	8.400	9.000	E2	0.331	0.354



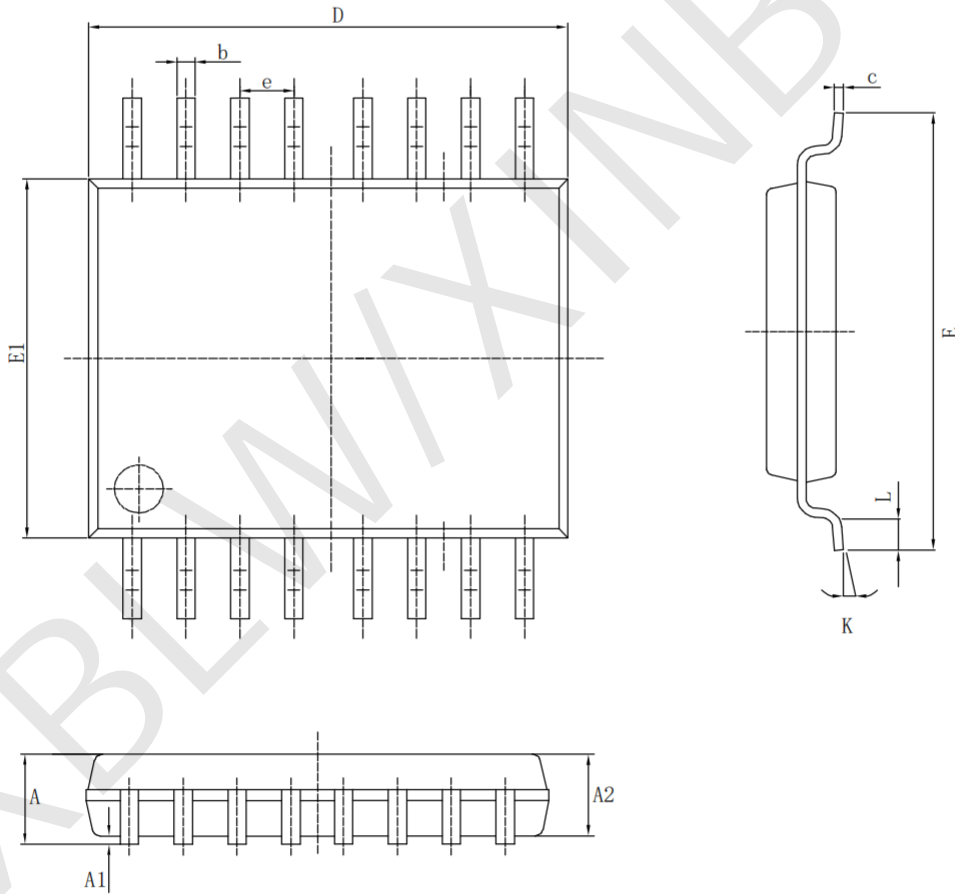
· SOP-16

Size Symbol	Dimensions In Millimeters			Size Symbol	Dimensions In Inches		
	Min (mm)	Nom (mm)	Max (mm)		Min (in)	Nom (in)	Max (in)
A	1.500	1.600	1.700	A	0.059	0.063	0.067
A1	0.100	0.150	0.250	A1	0.004	0.006	0.010
A2	1.400	1.450	1.500	A2	0.055	0.057	0.059
A3	0.600	0.650	0.700	A3	0.024	0.026	0.028
b	0.300	0.400	0.500	b	0.012	0.016	0.020
c	0.150	0.200	0.250	c	0.006	0.008	0.010
D	9.800	9.900	10.00	D	0.386	0.390	0.394
E	5.800	6.000	6.200	E	0.228	0.236	0.244
E1	3.850	3.900	3.950	E1	0.152	0.154	0.156
e	1.27 (BSC)			e	0.050 (BSC)		
L	0.500	0.600	0.700	L	0.020	0.024	0.028
L1	1.05 (BSC)			L1	0.041 (BSC)		
θ	0°	4°	8°	θ	0°	4°	8°



· TSSOP-16

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A		1.200	A		0.047
A1	0.050	0.150	A1	0.002	0.006
A2	0.800	1.050	A2	0.031	0.041
b	0.190	0.300	b	0.007	0.012
c	0.090	0.200	c	0.004	0.0089
D	4.900	5.100	D	0.193	0.201
E	6.200	6.600	E	0.244	0.260
E1	4.300	4.480	E1	0.169	0.176
e	0.65 (BSC)		e	0.0256 (BSC)	
K	0°	8°	K	0°	8°
L	0.450	0.750	L	0.018	0.030



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